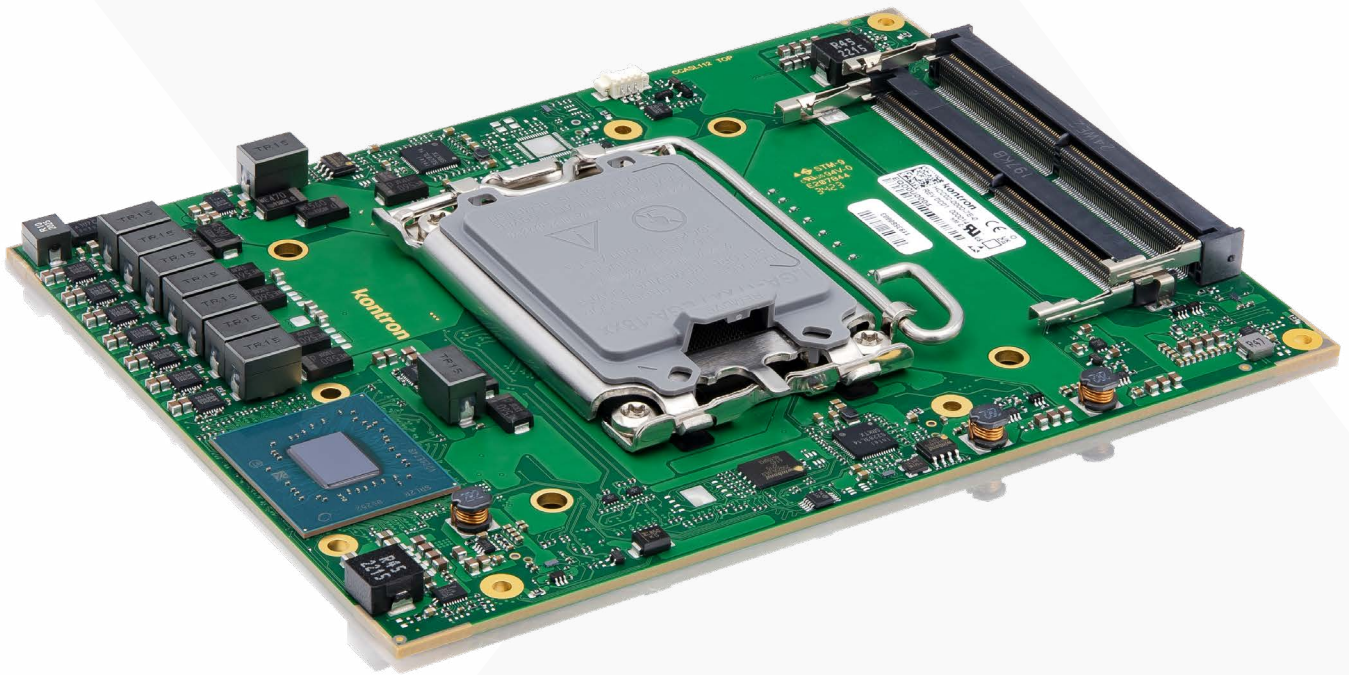
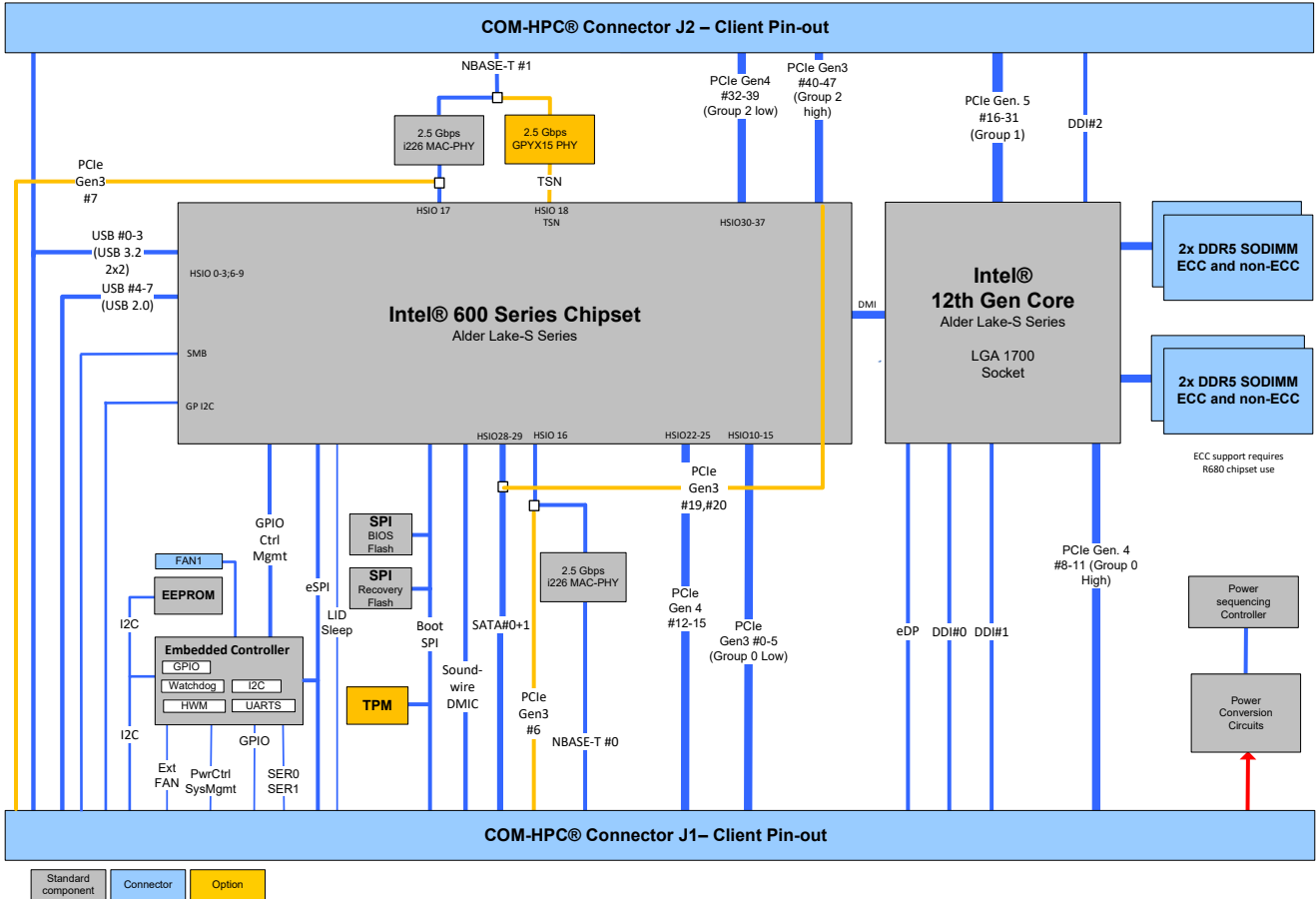




COM-HPC Client Size C module based on the 12th, 13th Gen and 14th Intel® Core™ S processors

- Up to 16 cores (TDP range: 35 W-65 W) & 24 threads
- Memory: Max 128 GByte DDR5 via 4x SODIMMs, ECC and non-ECC
- 16x PCIe Gen 5.0 lanes (for high performance CPUs) + 8x PCIe Gen 4.0 lanes + 6x PCIe Gen 3.0 lanes
- 3x DDI + 1x eDP

COMPLIANCE	COM HPC® Size C Client
DIMENSIONS	160 x 120 mm
CPU (SoC)	Intel® Core™ "Alder Lake S", Raptor Lake S" and "Raptor Lake S Refresh" Processor Series For details see table "Variants" given below
CHIPSET	See table
MAIN MEMORY	2x DDR5 SODIMM for up to 64 GByte ECC / non ECC on request: 4x DDR5 SODIMM for up to 128 GByte ECC / non ECC
ETHERNET CONTROLLER	2x Intel® I226 or 1x Intel® I226, 1x integrated MAC with GPHY215
ETHERNET	2x 2.5 Gb Ethernet
STORAGE	2x SATA 6Gb/s
FLASH ONBOARD	-
PCI EXPRESS®	16x PCIe Gen 5.0 lanes (for high performance CPUs) + 8x PCIe Gen 4.0 lanes + 6x PCIe Gen 3.0 lanes
USB	4x (2x) USB 3.2
SERIAL	2x serial interface (RX/TX/CTS/RTS)
OTHER FEATURES	SPI, SMB, Fast I²C, Staged Watchdog, RTC
SPECIAL FEATURES	TPM 2.0
FEATURES ON REQUEST	additional 3rd and 4th SODIMM socket
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	12 V ATX and/or Single Supply Power
BIOS	AMI UEFI
OPERATING SYSTEM	Linux, Windows 11
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating -30 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)



Variants

PART NO.	ARTICLE	CPU	CHIPSET
HCC02-1410-7E-3	COMh-ccAS i3-14100	i3-14100	Q670E
HCC02-1450-8E-5	COMh-ccAS i5-14500	i5-14500	R680E
HCC02-1470-8E-7	COMh-ccAS i7-14700	i7-14700	R680E
HCC02-1490-8E-9	COMh-ccAS i9-14900	i9-14900	R680E

Please contact tech support for custom UEFI firmware

Carrier

ARTICLE	PART NO.	DESCRIPTION
COM-HPC CLIENT CARRIER 10MM	HCT01-0000-10-0	COM-HPC Client Carrier with 10mm Connector Height

ARTICLE	PART NO.	DESCRIPTION
COMh-ccAS HEAT SPREADER THREADED	HCC0A-0000-99-0	Standard COM-HPC Heat Spreader for COMh-ccAS with threads
COMh-ccAS HEAT SPREADER THROUGH HOLE	HCC0A-0000-99-1	Standard COM-HPC Heat Spreader for COMh-ccAS through hole
COMh-ccAS X-BRACKET	HCC0A-0000-99-2	X-Shape Bracket for Standard Motherboard Cooler
COMh-ccAS PCH COOLER	HCC0A-0000-99-3	PCH Cooler for COMh-ccAS
COMh-ccAS COOLING KIT 65W	HCC0A-0000-99-4	Motherboard CPU Cooler + X-Bracket + PCH Cooler
COMH-CCAS COOLER MOUNTING JACKET	HCC0A-0000-99-5	Needs to be used instead of X-Bracket, when 4th memory module is in use

Memory

PART NO.	MIN. SPEC.	SIZE	ECC/NON-ECC	OP. TEMPERATURE
97040-0848-CCAS	DDR5-4800	8 GByte	No ECC	0 °C to +60 °C
97040-1648-CCAS	DDR5-4800	16 GByte	No ECC	0 °C to +60 °C
97040-3248-CCAS	DDR5-4800	32 GByte	No ECC	0 °C to +60 °C
97050-0848-CCAS	DDR5-4800	8 GByte	ECC	0 °C to +60 °C
97050-1648-CCAS	DDR5-4800	16 GByte	ECC	0 °C to +60 °C
97050-3248-CCAS	DDR5-4800	32 GByte	ECC	0 °C to +60 °C

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